



## Single Channel Linear Constant Current LED Driver ME8608-N2

### Description

ME8608-N2 is a single channel linear constant current LED driver which integrates a 500V high-voltage MOSFET inside. The output current can be accurately set by RSET. The chip can be used to drive LED strips supplied by commercial power. The system is simple with few peripheral components. Thus, the cost is low.

ME8608-N2 integrates over temperature protection (OTP) function. When output voltage or current is too high, the temperature of the chip rises. The OTP function can reduce the current through LED to prevent the thermal damage.

### Features

- Over temperature protection
- Ultra-fast LED start up
- Internal 500V MOSFET
- Output current can be set by RSET, range from 5mA to 60mA
- Simple external circuit
- Sharing PCB with LED

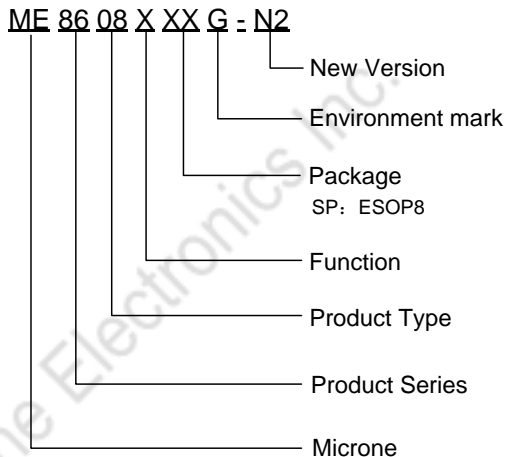
### Application

- LED bulb lamp
- LED fluorescent lamp
- LED street lighting

### Package

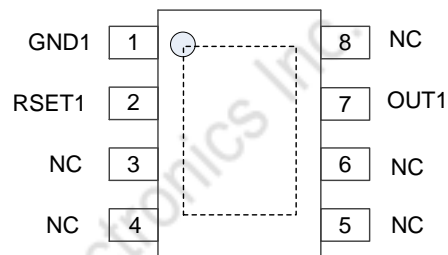
- 8-pin ESOP8

## Selection Guide



Product Series	Product Description
ME8608BDSPG-N2	OTP: 130°C; Package:ESOP8(single die)

## Pin Configuration



ESOP8(single die)

## Pin Assignment

PIN Number (ESOP8)	Symbol	Function
1	GND1	Ground
2	RSET1	Output current setting pin, connect to Ground with a resistor
3、4、5、6、8	NC	Empty Foot
7	OUT1	Connect to LED lamps, voltage input and constant current output

## Functional Block Diagram

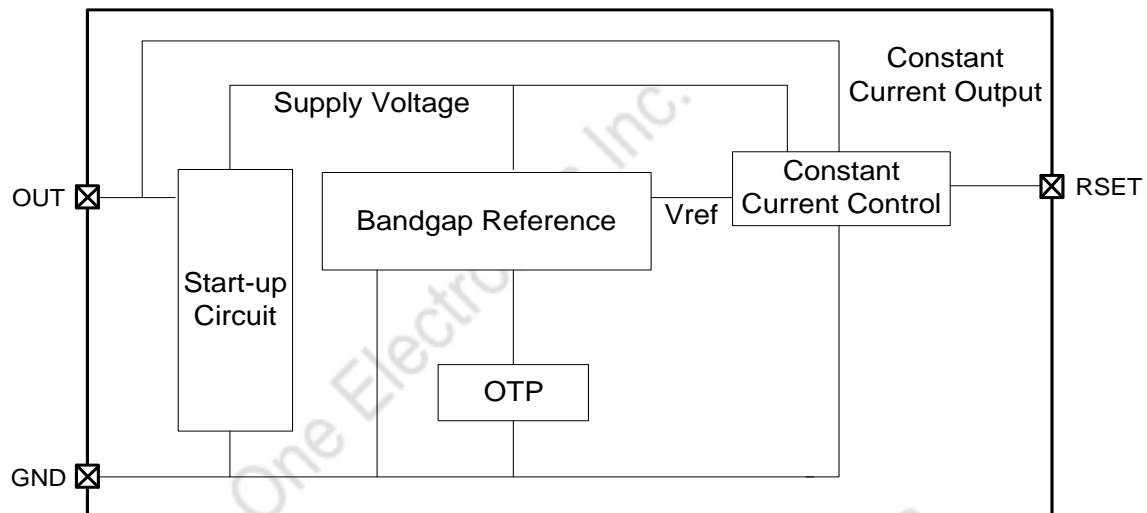


Figure 1. Functional Block Diagram of ME8608-N2

## Absolute Maximum Ratings <sup>(1)</sup>

Parameter		Value	Unit
Voltage at OUT: $V_{OUT}$		-0.5~500	V
Current at OUT: $I_{OUT}$		5~60	mA
Operating Ambient Temperature		-40~+85	°C
Storage Temperature		-55~+150	°C
Maximum junction temperature		-40~+150	°C
Thermal resistor <sup>(2)</sup>	ESOP8	63	°C/W
Continuous Total Power Dissipation $P_D$	ESOP8	1.98	W

Note: (1) Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These values must therefore not be exceeded under any conditions.

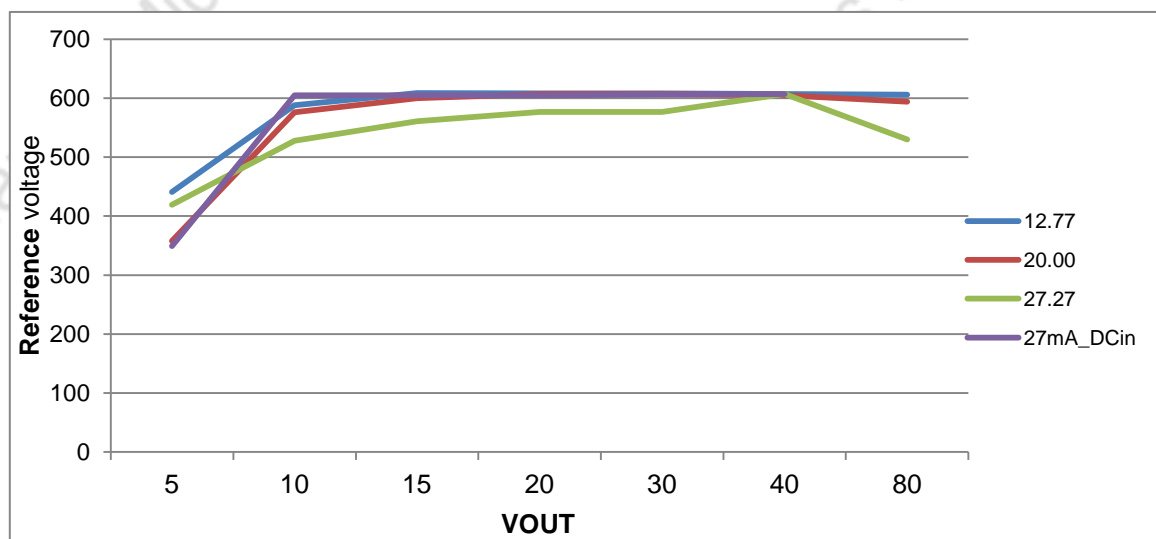
(2) ME8608-N2 needs to be connected to the PCB with at least 200mm<sup>2</sup> cooling copper foil, the thickness of the copper foil is 35µm.

## Electrical Characteristics (T<sub>A</sub>=25°C, unless otherwise specified)

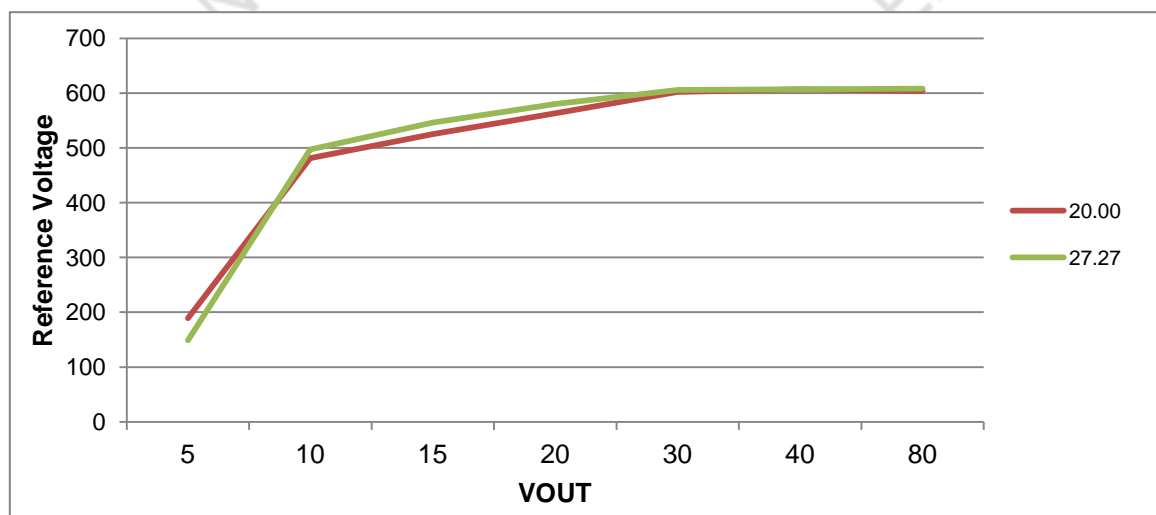
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V <sub>OUT</sub>	Out Terminal Open voltage	Out Terminal voltage at 95% LED current setting	-	6.5	-	V
V <sub>OUT-BV</sub>	Break Down Voltage	RSET is opened	480	-	-	V
I <sub>OUT</sub>	Output Current (3)	V <sub>OUT</sub> =10V	5	-	100	mA
I <sub>DD</sub>	Quiescent Current	RSET is opened(V <sub>OUT</sub> =10V)	0.033	0.046	0.059	mA
V <sub>RSET</sub>	Voltage of RSET	V <sub>OUT</sub> =10V, RSET =120Ω	0.555	0.582	0.609	V
T <sub>sc</sub>	Initial point of negative Temperature compensation	Chip junction temperature when LED current drops to 95% set value	-	150	-	°C

Note: (3) P<sub>max</sub> is the maximum power under good heat dissipation condition.

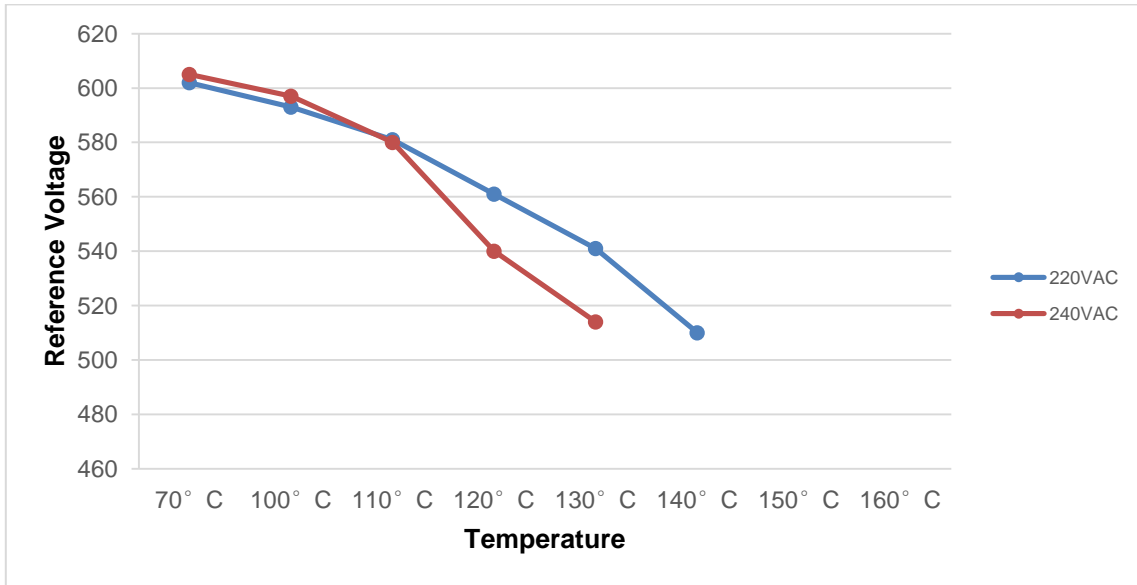
## Typical Performance Characteristic



Variation of reference voltage of different load (mA) with V<sub>OUT</sub> (no heat dissipation bottom plate)



Variation of reference voltage of different load (mA) with V<sub>OUT</sub> (with heat dissipation bottom plate)



Variation of reference voltage with temperature

If the temperature of LED lamp is too high, the life span of LED will decrease. ME8608-N2 integrates temperature compensation. When the interior temperature of the chip exceeds 130°C, the output current will decrease automatically to lower down the internal temperature of LED lamp.

## Operation Description

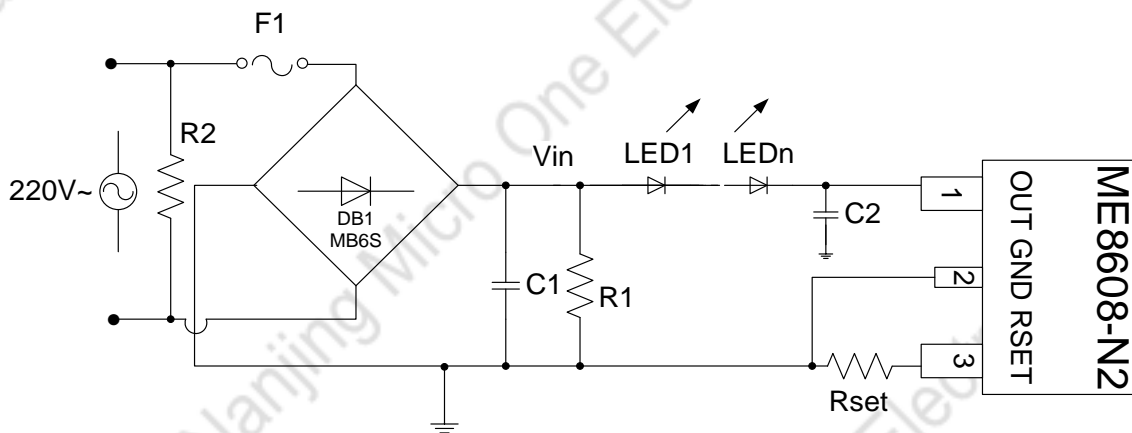


Figure 2. The ME8608-N2 Principle of Application

## Calculation of Output Current

The output current  $I_{OUT}$  is determined by the resistor between RSET and GND, the formula is shown as below:

$$I_{OUT} = \frac{V_{SET}}{R_{SET}}$$

$V_{SET}$  is the voltage between RSET and GND.

## Theory of Efficiency Design

The efficiency of the circuit can be obtained as below:

$$\eta = \frac{P_{LED}}{P_{in}} = \frac{n * V_{LED} * I_{LED}}{V_{in} * I_{LED}} = \frac{n * V_{LED}}{V_{in}} = \frac{V_{in} - V_{OUT}}{V_{in}}$$

The voltage of OUT is determined by the number of cascaded LED lamps and  $V_{in}$ ,  $V_{OUT}=V_{in}-nV_{LED}$ .  $V_{LED}$  is the voltage drop of a single LED,  $V_{in}$  is the input voltage of the system. From the formula above, we know that with the increase number of LED lamps,  $V_{OUT}$  decreases and the efficiency increases. In the system design, we need to optimize the efficiency performance by adjust the voltage of OUT.

## Selection of Number of LED Lamps

The voltage of OUT should be larger than  $V_{OUT\_MIN}$  to make sure the chip operates properly. The range of  $V_{OUT}$  is  $V_{OUT\_MIN}\sim V_{OUT\_MAX}$ , the number of cascaded LED lamps range from  $\frac{V_{in} - V_{OUT\_MAX}}{V_{LED}}$  to  $\frac{V_{in} - V_{OUT\_MIN}}{V_{LED}}$ .

## Selection of Capacitor and Resistor

$C_1$  is electrolytic capacitor;  $C_2$  is anti-interference device, which is optional, the recommended value is 10nF/10KV;  $R_1$  is the discharging resistor of the system, the recommended range is 510K $\Omega$ ~1M $\Omega$ ;  $R_2$  is a varistor to prevent surge damage to the chip. Recommended model 7D741.

$C_1$  can reduce the ripple voltage of  $V_{in}$ , the larger the  $C_2$ , the smaller the ripple of  $V_{in}$  and the ripple of the voltage of OUT is smaller too.  $C_1$  is related to the total current flows through the LED lamps, typical range of  $C_1$  is 4.7 $\mu$ F/400V~22 $\mu$ F/400V and the formula is shown as below:

$$C_1 = \frac{I_{LED} \times t}{\Delta V}$$

$I_{LED}$  is the current through LED lamps, which equals to output current  $I_{OUT}$ ; When the frequency of AC power supply is 50Hz,  $t = \frac{1}{4} \times \frac{1}{f} = 5\text{ms}$ ;  $\Delta V$  is the ripple voltage of OUT.

## PCB Layout

When designing the PCB, please follow the guidelines showed as below to optimize performance:

- (1) Aluminum base board is preferred to achieve better thermal performance.
- (2) The connection of the power ground of the resistor  $R_{set}$  should be as shorter as possible to reduce the effect of parasitic resistor, which will decrease the error of output current.
- (3) Heat sink is on the bottom of ME8608-N2, connected to GND of the chip internally. The heat sink should be connected to the ground of PCB; it is recommended that the chip should be connected to PCB with at least 200mm<sup>2</sup> cooling copper foil, the thickness of the copper foil is 35 $\mu$ m.
- (4) The ME8608-N2 series is a linear drive scheme with internal thermal feedback adjustment, so the maximum drive current capability is directly related to the heat dissipation of the solution.

**Package Quantity**

Package Type	Minimum Packing QTY	UNITS	Small Box	Large BOX
ESOP8	3000	Tape & Reel	6K	48K

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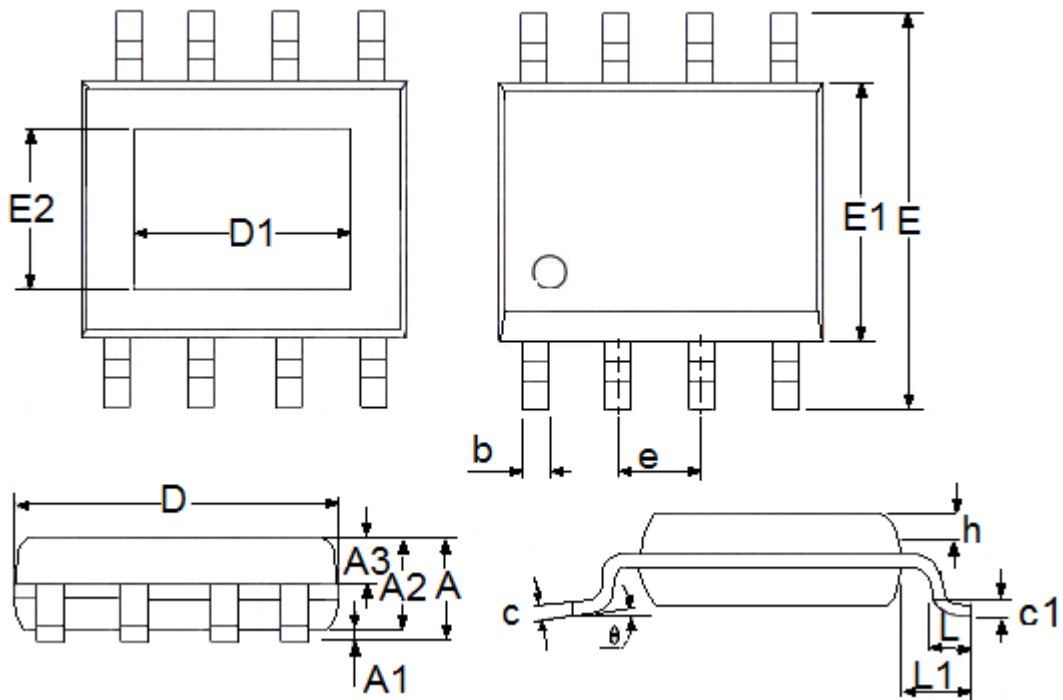
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## Package Information

Package Type: ESOP8



DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	1.3	1.75	0.0512	0.0689
A1	0	0.2	0.0000	0.0079
A2	1.25	1.65	0.0492	0.0650
A3	0.5	0.7	0.0197	0.0276
b	0.33	0.51	0.0130	0.0201
c	0.17	0.25	0.0067	0.0098
D	4.7	5.1	0.1850	0.2008
E	5.8	6.2	0.2283	0.2441
E1	3.8	4	0.1496	0.1575
e	1.27(TYP)		0.05(TYP)	
h	0.25	0.5	0.0098	0.0197
L	0.4	1.27	0.0157	0.0500
L1	1.04(TYP)		0.0409(TYP)	
$\theta$	0	8°	0.0000	8°
c1	0.25(TYP)		0.0098(TYP)	
D1	3.1(TYP)		0.122(TYP)	
E2	2.21(TYP)		0.087(TYP)	

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